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(54) **ULTRA SMALL MOLDED MODULE  
INTEGRATED WITH DIE BY  
MODULE-ON-WAFER ASSEMBLY**

(71) Applicant: **Intel Corporation**, Santa Clara, CA  
(US)

(72) Inventors: **Tomita YOSHIHIRO**, Tsukuba-shi  
(JP); **Eric J. LI**, Chandler, AZ (US);  
**Shawna M. LIFF**, Scottsdale, AZ (US);  
**Javier A. FALCON**, Chandler, AZ  
(US); **Joshua D. HEPPNER**, Chandler,  
AZ (US)

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**ABSTRACT**

Embodiments of the invention include molded modules and methods for forming molded modules. According to an embodiment the molded modules may be integrated into an electrical package. Electrical packages according to embodiments of the invention may include a die with a redistribution layer formed on at least one surface. The molded module may be mounted to the die. According to an embodiment, the molded module may include a mold layer and a plurality of components encapsulated within the mold layer. Terminals from each of the components may be substantially coplanar with a surface of the mold layer in order to allow the terminals to be electrically coupled to the redistribution layer on the die. Additional embodiments of the invention may include one or more through mold vias formed in the mold layer to provide power delivery and/or one or more faraday cages around components.

